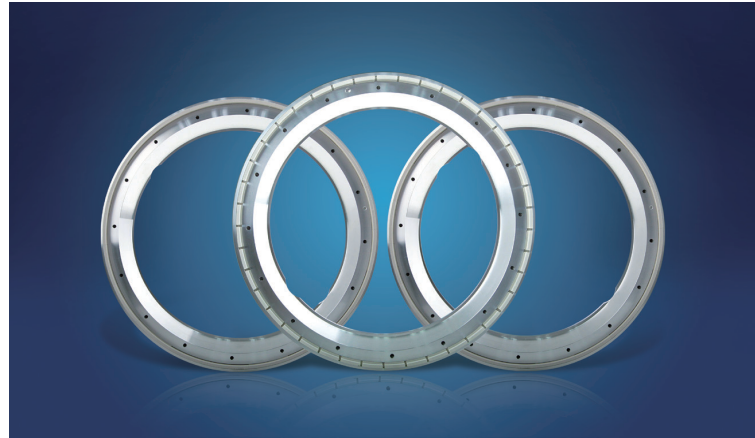


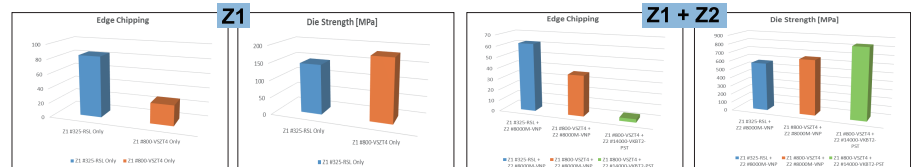
VITRIFIED BACK GRINDING WHEEL (NANO POL)



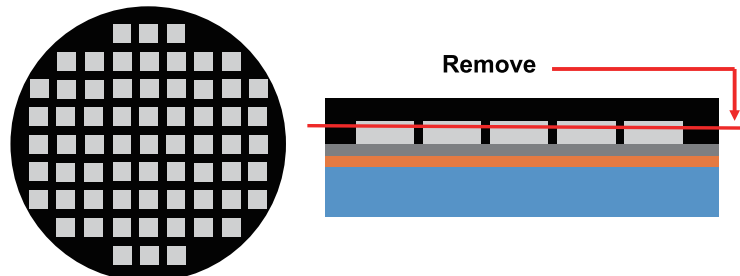
Technology

- Improve wafer surface roughness and die strength
- Reduce grinding stress and wafer edge chipping
- Diamond distribution at tip can be unified.
- Porosity, pore shape, and pore size controlling in various ways.
- Solution capable of grinding ultra thin wafer up to 17 μ m
- Solution for compound wafer grinding for TSV

Si Wafer Grinding Wheel



Compound Material & Compound Molded Wafer (TSV/Fan-Out) Grinding Wheel



Material	Wheel Spec.
Pure Compound(Ex. EMC)	#800 ~ #2000 VSP3, #800 ~ #2000 VSP5
Compound + Silicon Chip	Z1 #800 VSP3 + Z2 #5000VK8HS, Z1 #800 VSP3 + Z2 #5000VK8B
Compound + Silicon Chip + Copper Via	Z1 #800 VSP3 + Z2 #5000VK8HS, Z1 #800 VSP3 + Z2 #5000VK8B
Compound + Silicon Chip + Copper Via + Polyimide + Solder	Z1 #800 VSP3 + #3000 VSPS10, Z1 #800 VSP3 + #3000 VSPBT7

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